

**IN THE UNITED STATES
PATENT AND TRADEMARK OFFICE**

Attorney Docket No.: TREUSCH - 4
TITLE Stepped Microchannel Heat Sink
Application No.:
Filing Date:
Group Art Unit:

Commissioner for Patents
P. O. Box. 1450
Alexandria, VA 22313-1430

INFORMATION DISCLOSURE STATEMENT

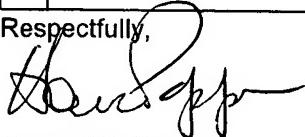
Herewith the Information Disclosure Statement Pursuant to 37 CFR 1.98. Copies of the cited documents are enclosed.

Number	Date	Inventor	Assignee	Class	Notes
6480514	11/12/2002	Lorenzon	Jen Optik	372/35	μ -ch
6312166	11/06/2001	Zediker	Nuvonyx	385/88	vertical stack array
6229831	05/08/2001	Nightingale	Coherent	372/36	Stepped heat sink
5987043	11/16/1999	Brown	Opto Power	372/36	Stepped heat sink Figs 4-8
5848083	12/08/1998	Huden	SDL	372/36	Fig. 2E etched channels 134 in sheets 132
5212707	05/18/1993	Heidel	McDonnell Douglas	372/50	
5107091	04/21/1992	Wagner	Applied Solar Energy		μ -ch
5105430	04/14/1992	Mundinger	US DOE	372/35	μ -ch
5099910	03/31/1992	Walpole	MIT	165/80. 4	High speed dicing sawed Si (or CuW) μ -ch
5099311	03/24/1992	Bonde	US DOE	357/82	Si μ -ch
5005640	04/09/1991	Lapinski	McDonnell Douglas	165.160	μ -ch grooves sawed plates 4, 16
4494171	01/15/1985	Bland	Sunstrand	361/386	Diffusion bonded .010 plates, Impingement cooling
4345643	08/24/1982	Dawson	US DOD	165/122	Air-cooled plate array

DE 2153969 5/1973 Stepped heat sink

JP 4-264789 9/1992 Stepped heat sink

Respectfully,



Howard R. Popper
Reg. No. 19,208

Attorney for Applicant Dated: September 19, 2003

Examiner: _____